

**Surface Mount Standard Recovery
Glass Passivated**

**REVERSE VOLTAGE
50 TO 1000 VOLTS
FORWARD CURRENT
1.0 AMPERE**

Features:

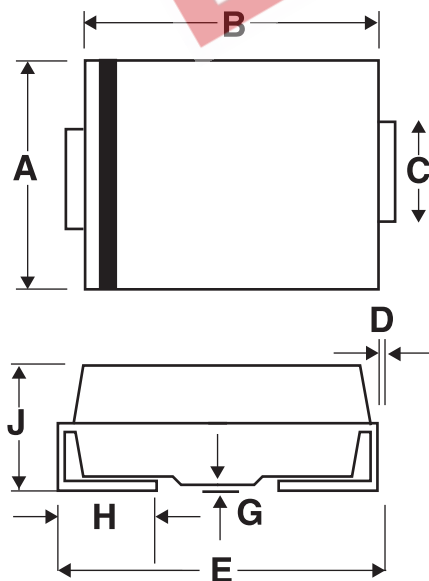
- *For Surface Mount Application
- *Glass Passivated Chip
- *Low Reverse Leakage Current
- *Low Forward Voltage Drop And High Current Capability
- *Plastic Material Has UL Flammability Classification 94V-0


SMB(DO-214AA)
Mechanical Data

- *Case : Molded Plastic
- *Polarity :Indicated by cathode band
- *Weight : 0.003 Ounce ,0.093 grams

SMB Outline Dimensions

Unit:mm



SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.80
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62

Maximum Ratings and Electrical Characteristics

Rating 25°C Ambient Temperature Unless Otherwise Specified.

Single Phase Half Wave, 60Hz , Resistive or Inductive Load.

For Capacitive Load, Derate Current by 20%.

Characteristics	Symbol	S1AB	S1BB	S1DB	S1GB	S1JB	S1KB	S1MB	Unit
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @TC=100°C	IF(AV)	1.0							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	IFSM	30							A
Maximum Instantaneous At 1.0A DC	VF	1.10							V
Maximum DC Reverse Current @Tj=25°C At Rated DC Blocking Voltage @Tj=125°C	IR	5.0 100							uA
Typical Junction Capacitance (Note 1)	C _J	10							PF
Typical Thermal Resistance (Note 2)	R _{θJL}	30							°C/W
Operating Temperature Range	T _J	-65 to+150							°C
Storage Temperature Range	TSTG	-65 to+150							°C

NOTES: 1.Measured at 1.0MHz applied reverse voltage of 4.0V DC.

2.Thermal Resistance Junction to case.

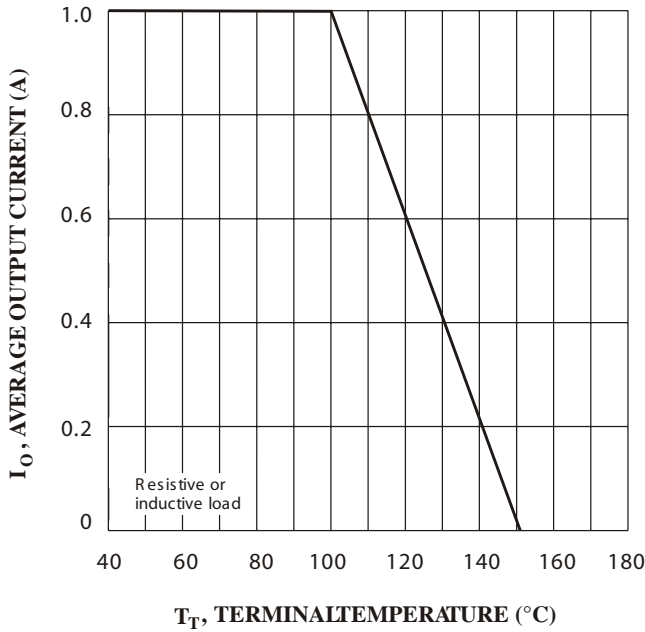


FIG1. Forward Current Derating Curve

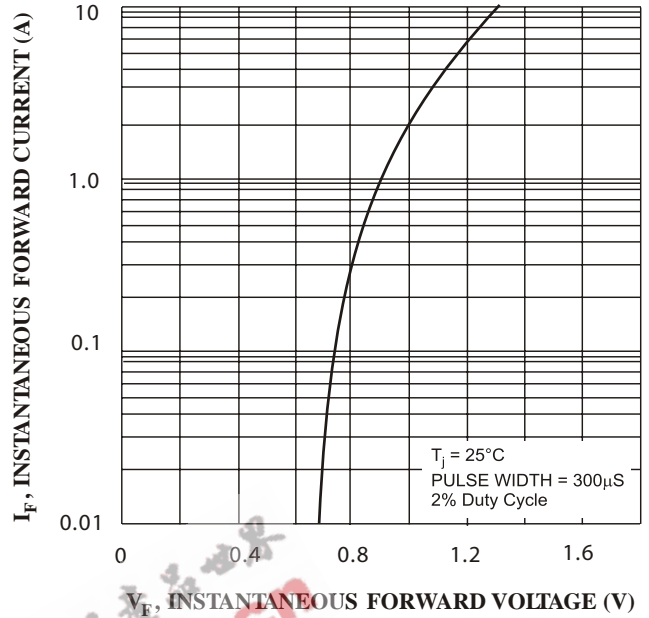


FIG2. Typical Forward Characteristics

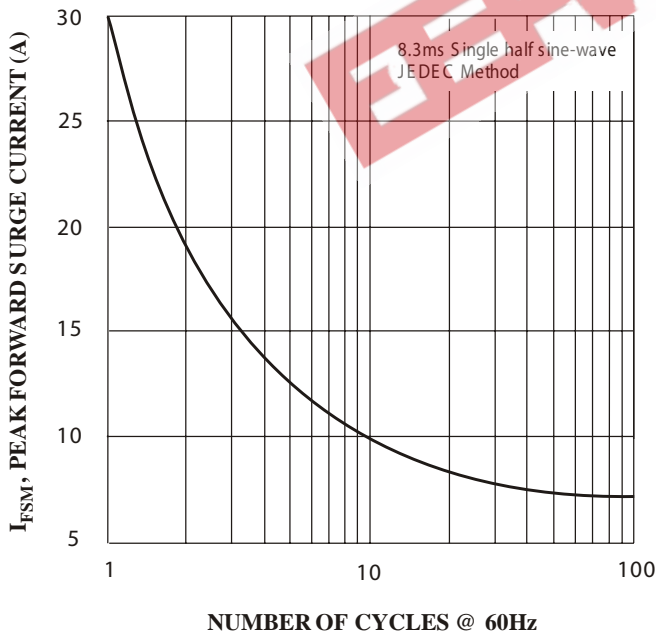


FIG3. Typical Forward Characteristics

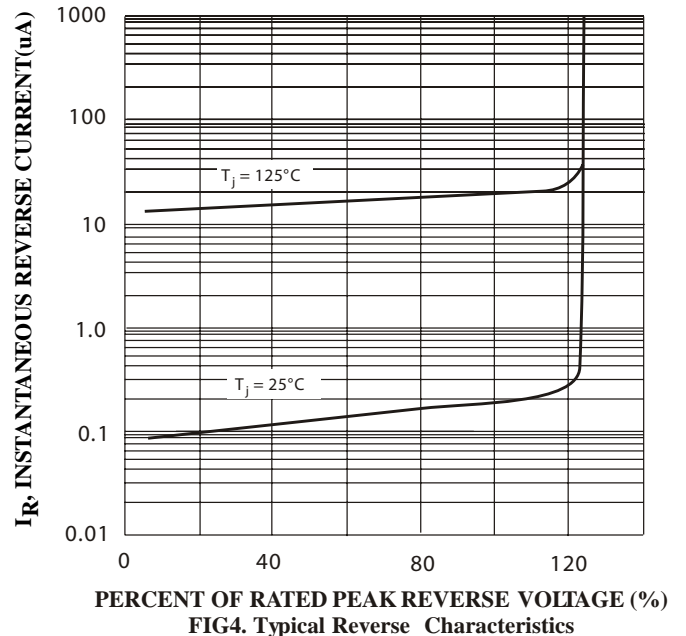


FIG4. Typical Reverse Characteristics